



**SURFACE MOUNT  
SCHOTTKY BARRIER RECTIFIERS**

**REVERSE VOLTAGE - 200 Volts  
FORWARD CURRENT - 1.0 Ampere**

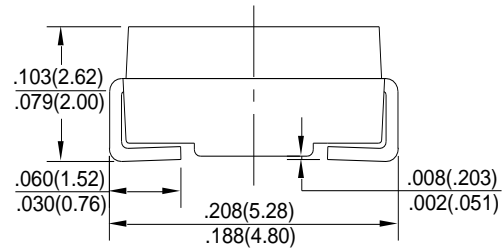
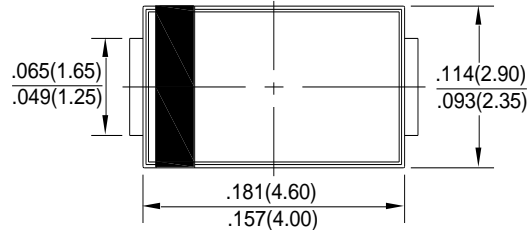
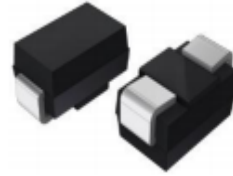
**FEATURES**

- For surface mounted applications
- Metal-Semiconductor junction with guarding
- Epitaxial construction
- Very low forward voltage drop
- High current capability
- Plastic material has UL flammability classification 94V-0
- For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications.

**MECHANICAL DATA**

- Case: Molded Plastic
- Polarity: Indicated by cathode band
- Weight: 0.002 ounces, 0.053 grams

**SMA**



Dimensions in inches and (millimeters)

**MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS**

Rating at 25°C ambient temperature unless otherwise specified.  
Single phase, half wave ,60Hz, resistive or inductive load.  
For capacitive load, derate current by 20%

CHARACTERISTICS	SYMBOL	SS120	UNIT
Maximum Recurrent Peak Reverse Voltage	VRRM	200	V
Maximum RMS Voltage	VRMS	140	V
Maximum DC Blocking Voltage	VDC	200	V
Maximum Average Forward Rectified Current @TL=100 °C	I(AV)	1.0	A
Peak Forward Surge Current 8.3ms Single Half Sine-Wave Super Imposed On Rated Load (JEDEC Method)	IFSM	30	A
Maximum Forward Voltage at 1.0A DC	VF	0.92	V
Maximum DC Reverse Current @Tj=25°C	IR	1.0	mA
at Rated DC Blocking Voltage @Tj=100°C		10	
Typical Junction Capacitance (Note1)	CJ	110	pF
Operating Temperature Range	TJ	-55 to + 150	°C
Storage Temperature Range	TSTG	-55 to + 150	°C

- NOTES: 1. Measured at 1.0 MHz and applied reverse voltage of 4.0V DC.  
2. Thermal resistance junction to lead.  
3. The typical data above is for reference only.

# RATING AND CHARACTERISTIC CURVES

## SS120

FIG. 1 - FORWARD CURRENT DERATING CURVE

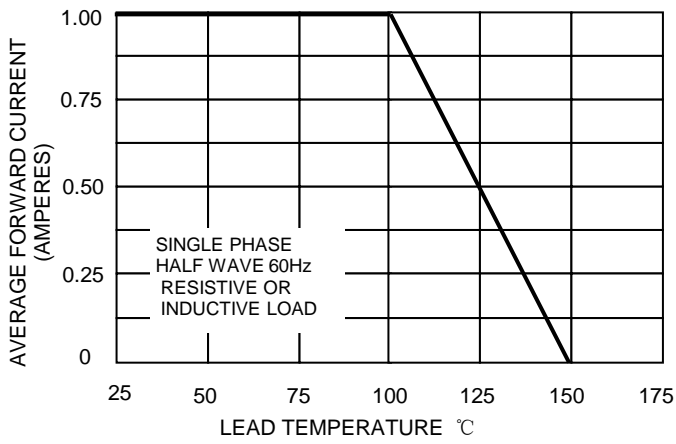


FIG. 2 - MAXIMUM NON-REPETITIVE SURGE CURRENT

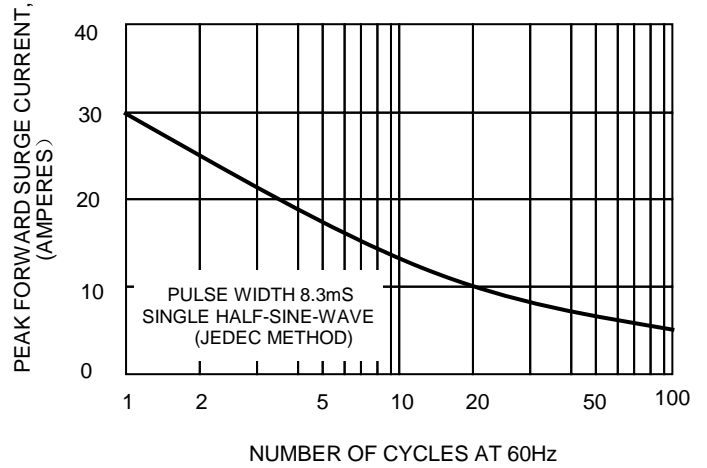


FIG.3-TYPICAL FORWARD CHARACTERISTICS

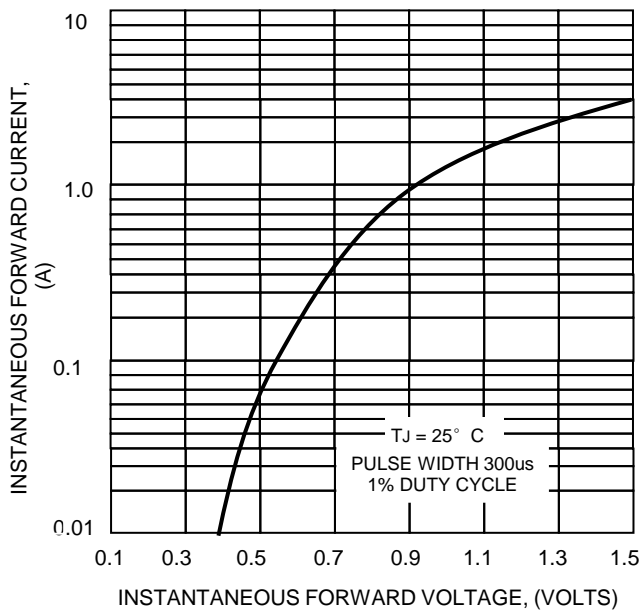


FIG.4-TYPICAL JUNCTION CAPACITANCE

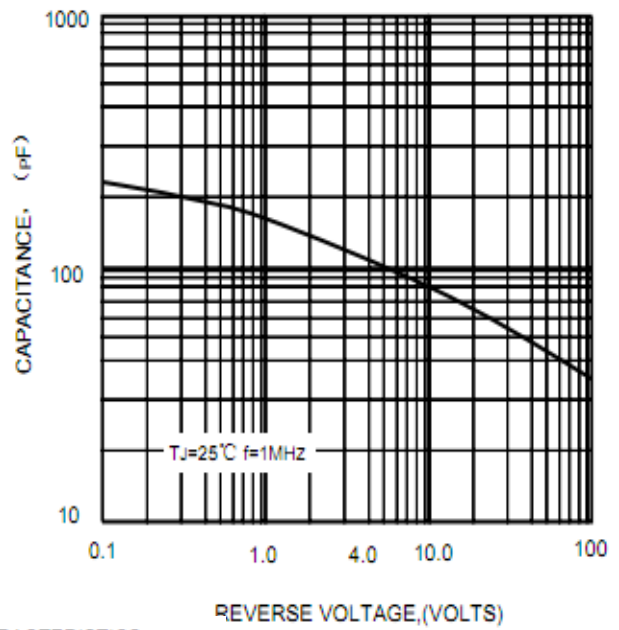
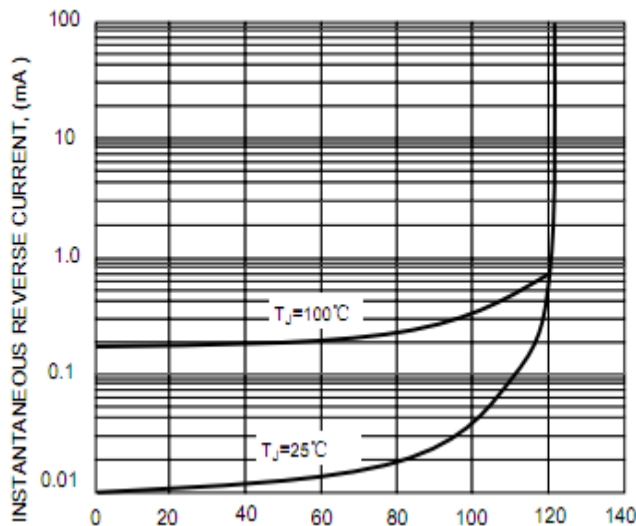


FIG.5-TYPICAL REVERSE CHARACTERISTICS



The cruve graph is for reference only.



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